



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE4999C8	Issued	25. June 2021
MA#	MA005559583		
Package	PG-TDSO-8-1	Weight*	66.72 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.822	1.23	1.23	12314	12314
leadframe	non noble metal	zinc	7440-66-6	0.062	0.09		928	
	non noble metal	tin	7440-31-5	0.077	0.12		1160	
	non noble metal	chromium	7440-47-3	0.093	0.14		1392	
	non noble metal	copper	7440-50-8	30.717	46.03	46.38	460420	463900
wire	noble metal	gold	7440-57-5	0.057	0.09	0.09	859	859
encapsulation	organic material	carbon black	1333-86-4	0.067	0.10		1003	
	plastics	epoxy resin	-	3.614	5.42		54174	
	inorganic material	silicondioxide	60676-86-0	29.784	44.64	50.16	446434	501611
leadfinish	non noble metal	tin	7440-31-5	0.497	0.75	0.75	7453	7453
plating	noble metal	silver	7440-22-4	0.793	1.19	1.19	11887	11887
glue	plastics	epoxy resin	-	0.033	0.05		494	
	plastics	acrylic resin	-	0.033	0.05		494	
	inorganic material	silicondioxide	60676-86-0	0.066	0.10	0.20	988	1976
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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